

Application: (Intel Core i5)

Intel LGA1156 Nehalem(45nm 95W) / Westmere (32nm 87W) CPU Lynnfield & Clarkdale sequence (Low Profile M/B mounting hole pitch 75x 75mm)

Picture:



Thermal & Mechanical Spec.:

Thermal performance for 95W & 87W CPU
 HSK Assembly Weight: 252 g (ref.)
 Clipping Force: 16 Kgf (ref.)

Component Specification:

- Heat Sink
 Type: Thermal Shrink with Cu Core
 Material: Aluminum A6063 & Copper C1100 or Equivalent.
 Dimension: 90*90*19.05 mm
- Thermal interface material
 Material: Dow Corning TC-1996 or Equivalent.
- Fan

(90x90x25 mm with Thermistor & PWM Control)

Rated Voltage: 12 V

Life Time:

Superflo bearing 50000 hrs

Connector:

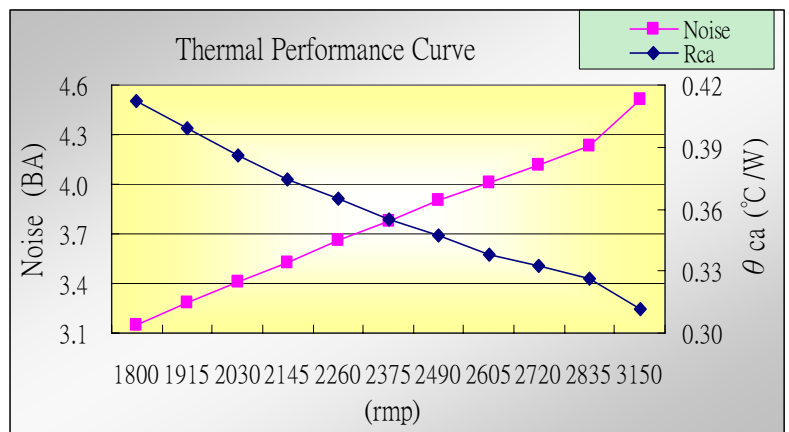
- Lead wire: UL 1430 AWG#26
 pin 1: black wire-----(-)
 pin 2: yellow wire-----(+)
 pin 3: green wire----- (F00)
 pin 4: blue wire----- (PWM)

b. Housing: Molex 47054-1000 or equivalent

c. Terminal: Molex 2759T 08-50-0113 or equivalent

* All readings are typical values at rated voltage.

* Specifications are subject to change without notice



Application: (Intel Core i3)

Intel LGA1156 Nehalem(45nm 82W) / Westmere (32nm73W) CPU Lynnfield & Clarkdale sequence (Low Profile M/B mounting hole pitch 75x 75mm)

Picture:



Thermal & Mechanical Spec.:

Thermal performance for 82W & 73W CPU
 HSK Assembly Weight: 205 g (ref.)
 Clipping Force: 16 Kgf (ref.)

Component Specification:

1. Heat Sink

Type: Extruded HSK
 Material: Aluminum A6063 or Equivalent.
 Dimension: 90*90*19.05 mm

2. Thermal interface material

Material: Dow Corning TC-1996 or Equivalent.

3. Fan

(90x90x25 mm with Thermistor & PWM Control)

Rated Voltage: 12 V

Life Time:

Superflo bearing 50000 hrs

Connector:

a. Lead wire: UL 1430 AWG#26

pin 1: black wire-----(-)

pin 2: yellow wire-----(+)

pin 3: green wire----- (F00)

pin 4: blue wire----- (PWM)

b. Housing: Molex 47054-1000 or equivalent

c. Terminal: Molex 2759T 08-50-0113 or equivalent

* All readings are typical values at rated voltage.

* Specifications are subject to change without notice

